# Quarterly Financial Result (Supplementary Materials)

Quarter 1: three months ended
March 31, 2026

May 13, 2026
Code: 6871

**MICRONICS JAPAN CO., LTD.**

# Disclaimer

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# Quarterly Financial Results (Q1)

# Consolidated Result Summary

(Unit : Mils. of Yen)
*Amounts less than one million yen are rounded down

| | FY12/2025 | | | | FY12/2026 | | | | |
|---|---|---|---|---|---|---|---|---|---|
| | Jan.-Mar. | Apr.-Jun. | Jul.-Sep. | Oct.-Dec. | Jan.-Mar. | QoQ | | YoY | |
| | Q1 ⓐ | Q2 | Q3 | Q4 ⓑ | Q1 ⓒ | (△) ⓒ-ⓑ | (%) | (△) ⓒ-ⓐ | (%) |
| Net Sales | 14,124 | 18,996 | 17,291 | 19,761 | 20,945 | +1,184 | +6.0% | +6,821 | +48.3% |
| Probe Card | 13,663 | 18,536 | 16,917 | 19,407 | 20,629 | +1,221 | +6.3% | +6,966 | +51.0% |
| TE | 460 | 460 | 374 | 353 | 316 | (37) | (10.5%) | (144) | (31.4%) |
| Gross Profit | 7,614 | 8,787 | 7,683 | 9,719 | 9,898 | +178 | +1.8% | +2,283 | +30.0% |
| Operating profit | 2,857 | 4,711 | 3,730 | 5,241 | 5,647 | +406 | +7.7% | +2,790 | +97.6% |
| Ordinary profit | 2,902 | 4,492 | 3,878 | 5,827 | 5,991 | +163 | +2.8% | +3,088 | +106.4% |
| Net Income Attributable to Owner of Parent | 1,673 | 3,101 | 2,309 | 4,978 | 4,392 | (586) | (11.8%) | +2,719 | +162.5% |

※ : Test Equipment

# Summary on Results

## Probe card

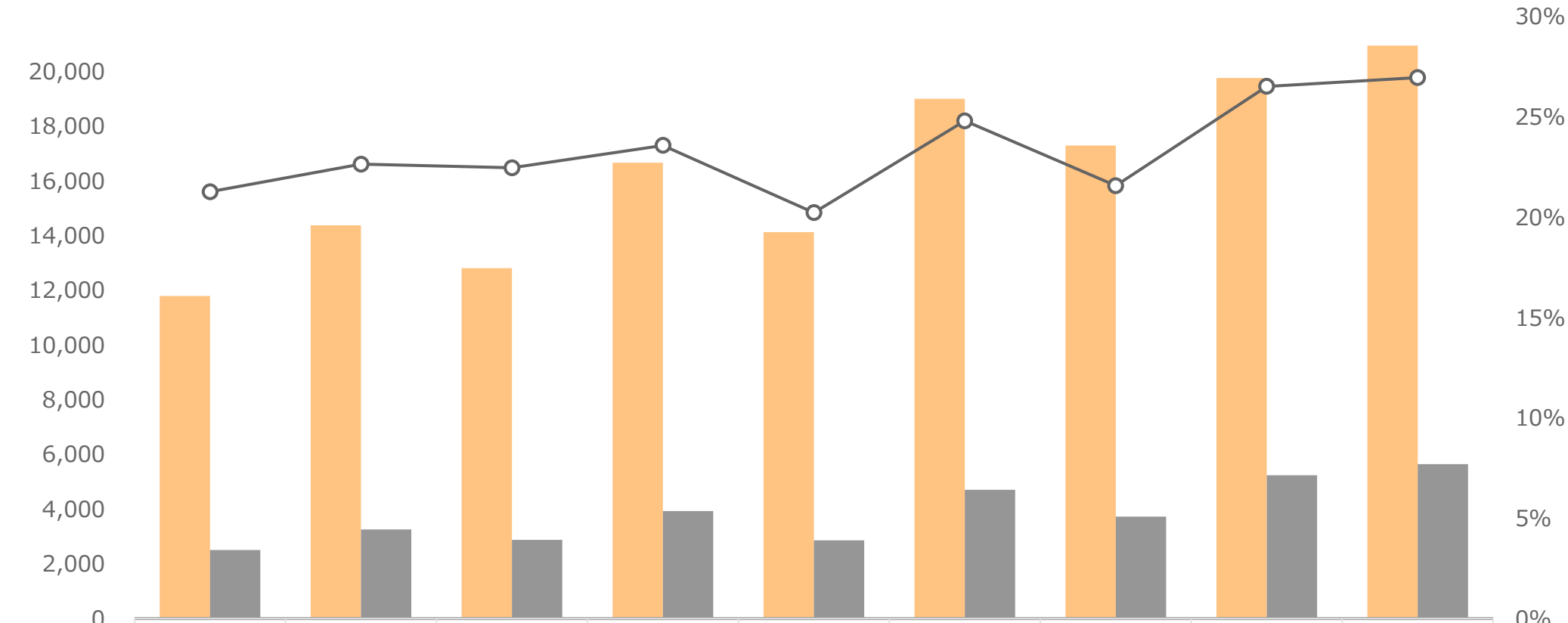
- Sales of memory probe cards reached a record high on a quarterly basis, mainly driven by the expansion of production capacity for DRAM applications.
- Sales of non-memory probe cards slightly increased compared to the previous quarter.
- Segment profit remained solid, supported by strong sales of DRAM probe cards.
- Although orders decreased compared to the previous quarter, high demand for DRAM, especially HBM, continues.

## TE

- Although semiconductor test sockets performed steadily, sales slightly decreased compared to the previous quarter.
- The segment recorded a loss.

# Quarterly Financial Result

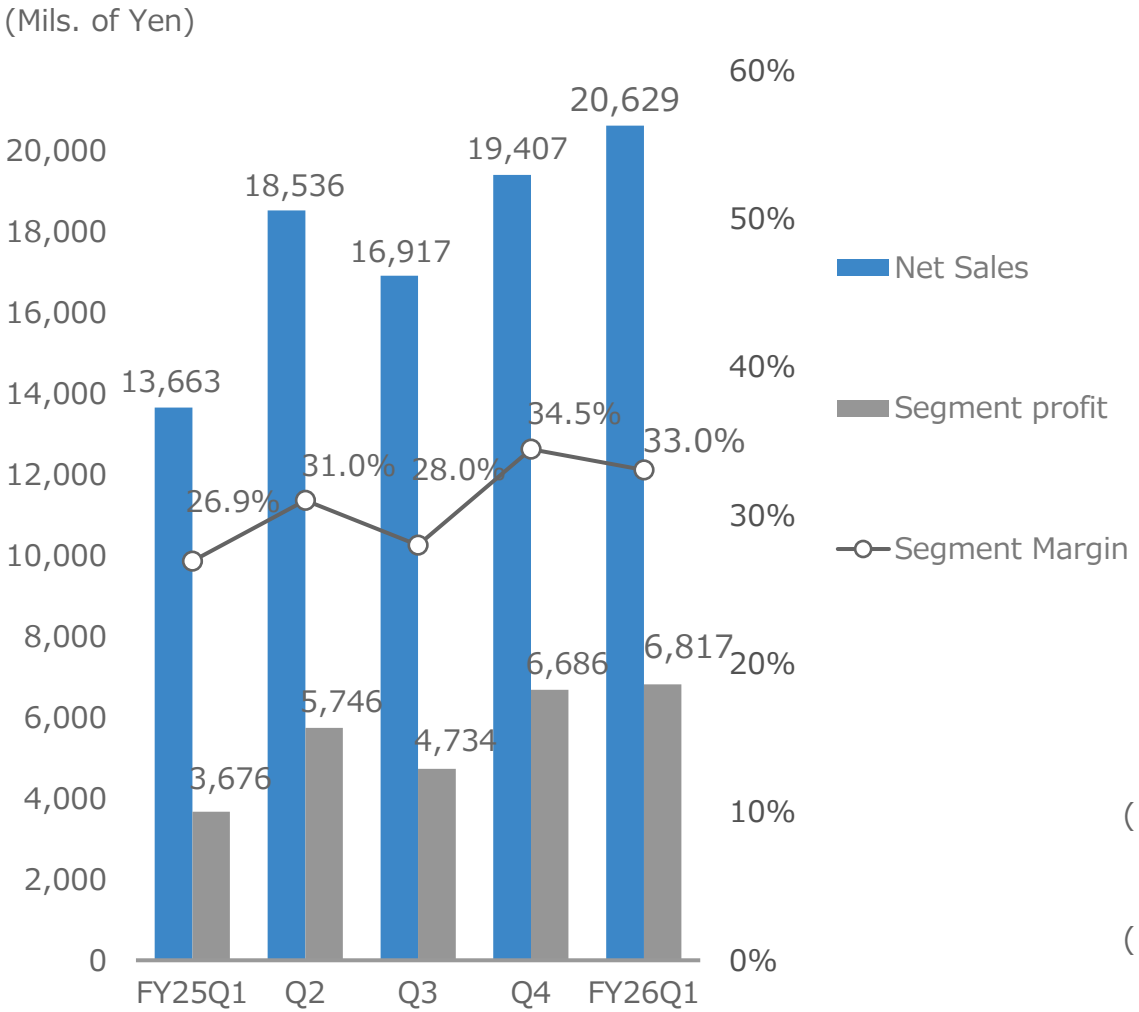
(Mils. of Yen)



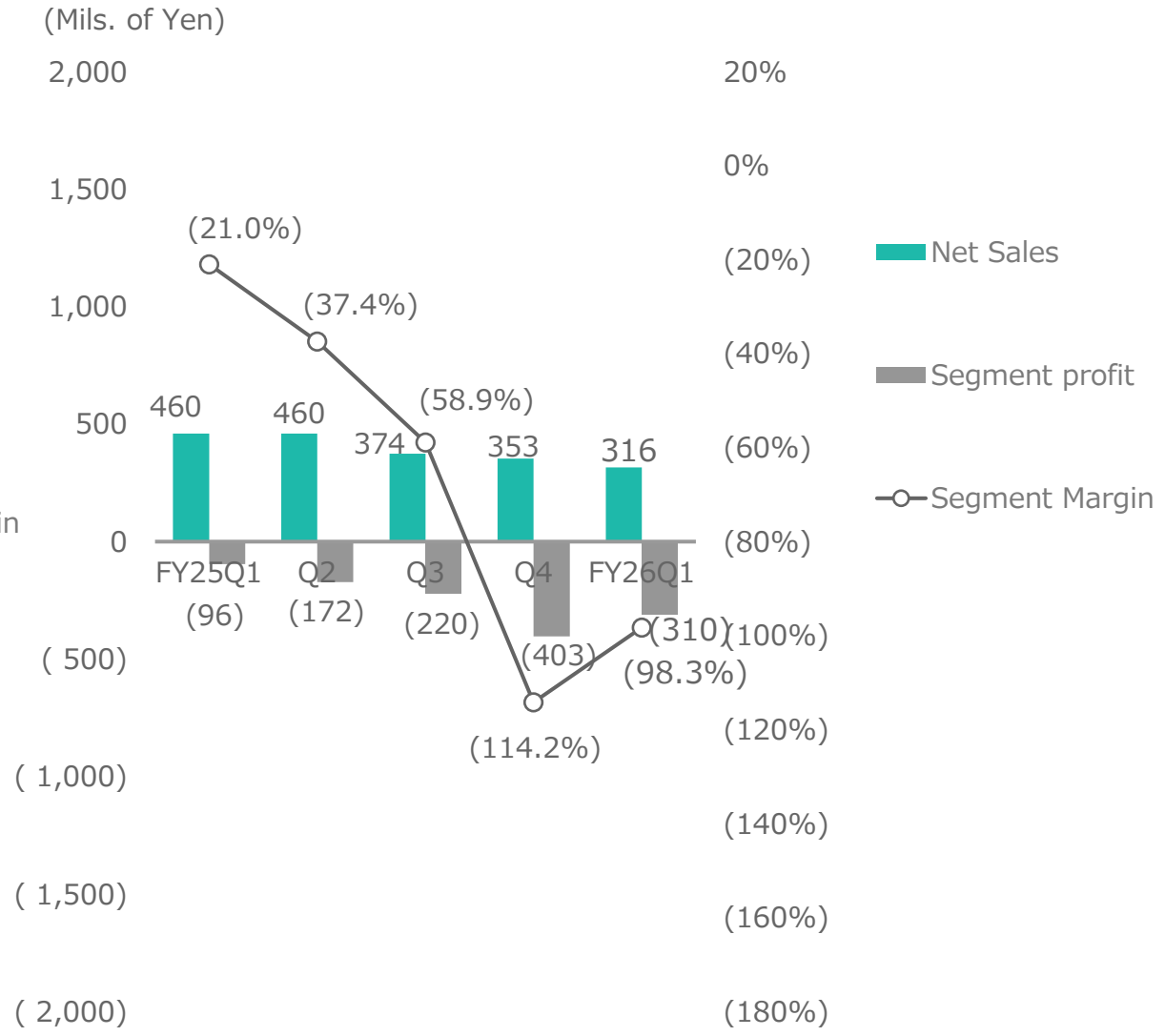

| | FY24Q1 | Q2 | Q3 | Q4 | FY25Q1 | Q2 | Q3 | Q4 | FY26Q1 |
|---|---|---|---|---|---|---|---|---|---|
| Net Sales | 11,794 | 14,376 | 12,812 | 16,659 | 14,124 | 18,996 | 17,291 | 19,761 | 20,945 |
| Operating profit | 2,508 | 3,255 | 2,878 | 3,928 | 2,857 | 4,711 | 3,730 | 5,241 | 5,647 |
| Operating Margin | 21.3% | 22.6% | 22.5% | 23.6% | 20.2% | 24.8% | 21.6% | 26.5% | 27.0% |

# Business Condition by Segment

## Probe card

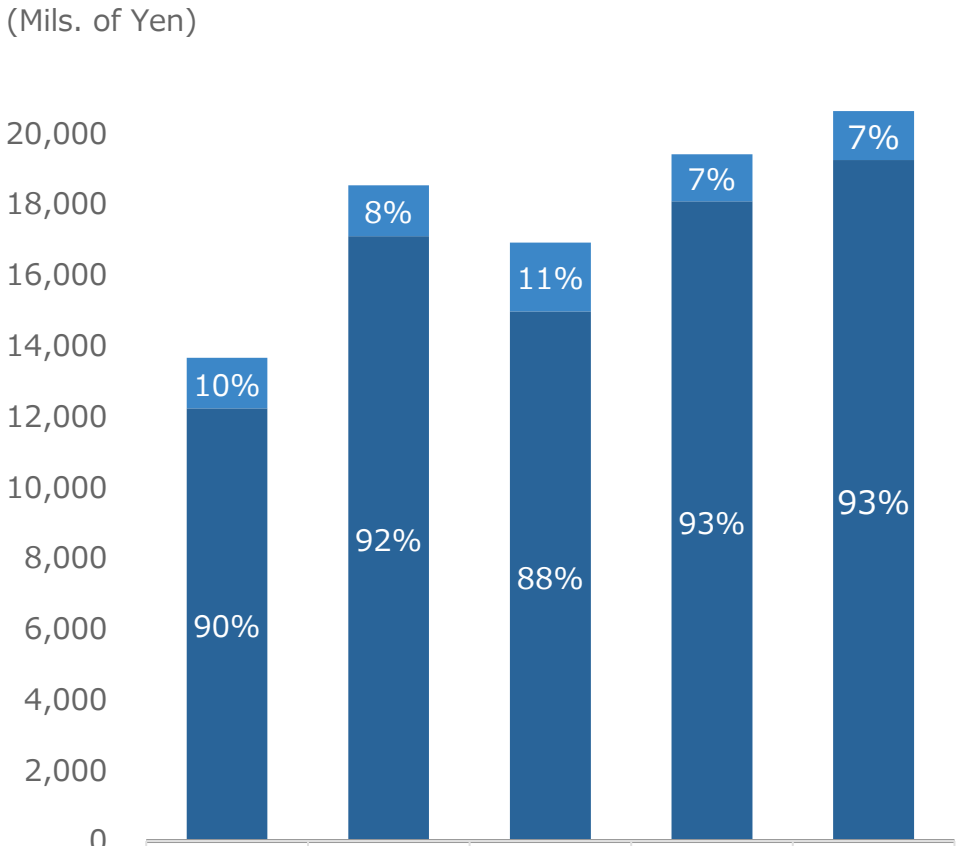



## TE



# Quarterly Net Sales by Product

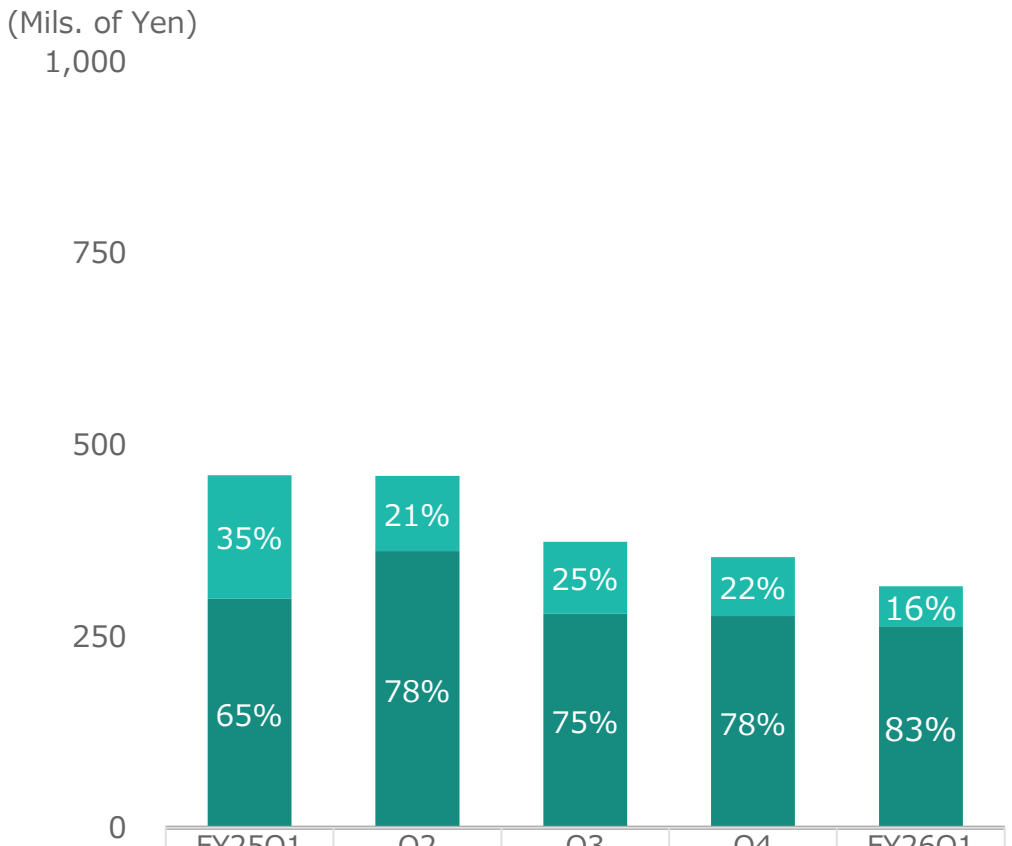
## Probe card




| | FY25Q1 | Q2 | Q3 | Q4 | FY26Q1 |
|---|---|---|---|---|---|
| Non-Memory | 1,432 | 1,437 | 1,945 | 1,329 | 1,383 |
| Memory | 12,230 | 17,098 | 14,971 | 18,078 | 19,245 |
| total | 13,663 | 18,536 | 16,917 | 19,407 | 20,629 |

※ Including sales of Cantilever type

## TE

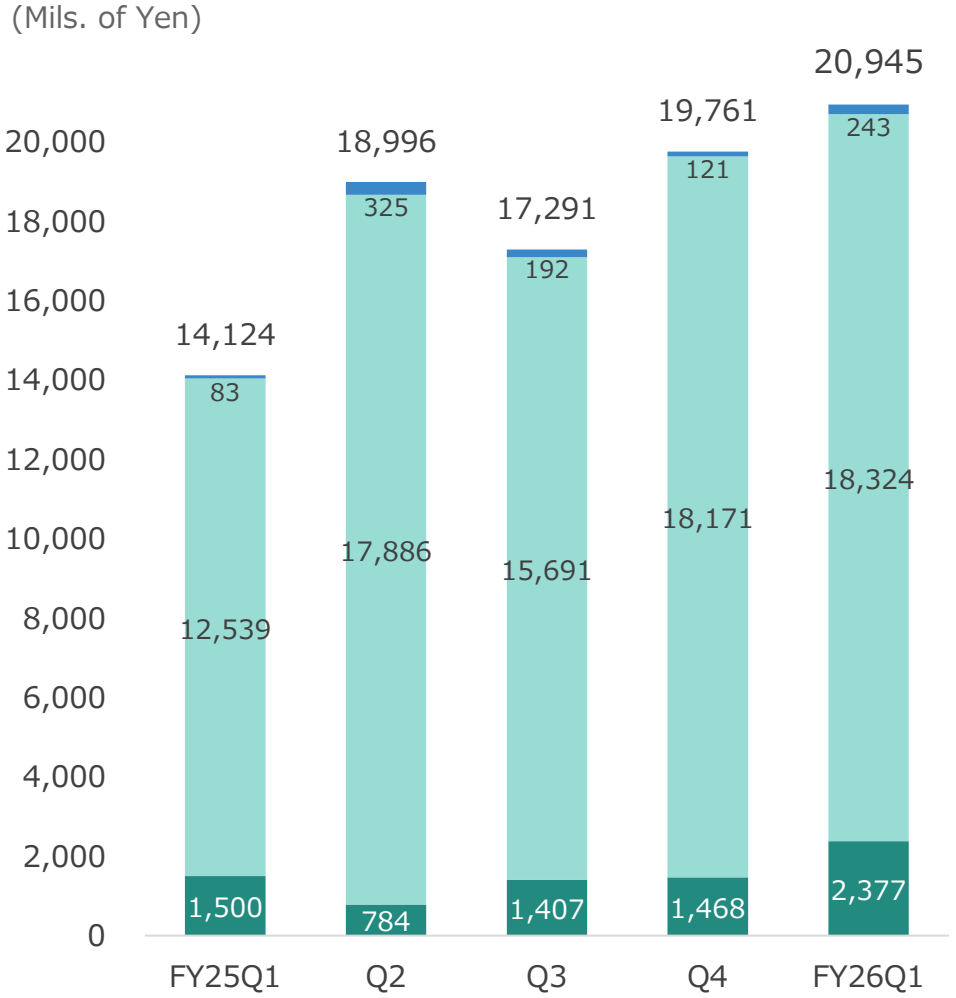



| | FY25Q1 | Q2 | Q3 | Q4 | FY26Q1 |
|---|---|---|---|---|---|
| Testing Equipment※1 | 161 | 98 | 94 | 77 | 52 |
| Testing Device ※2 | 299 | 361 | 279 | 276 | 263 |
| total | 460 | 460 | 374 | 353 | 316 |

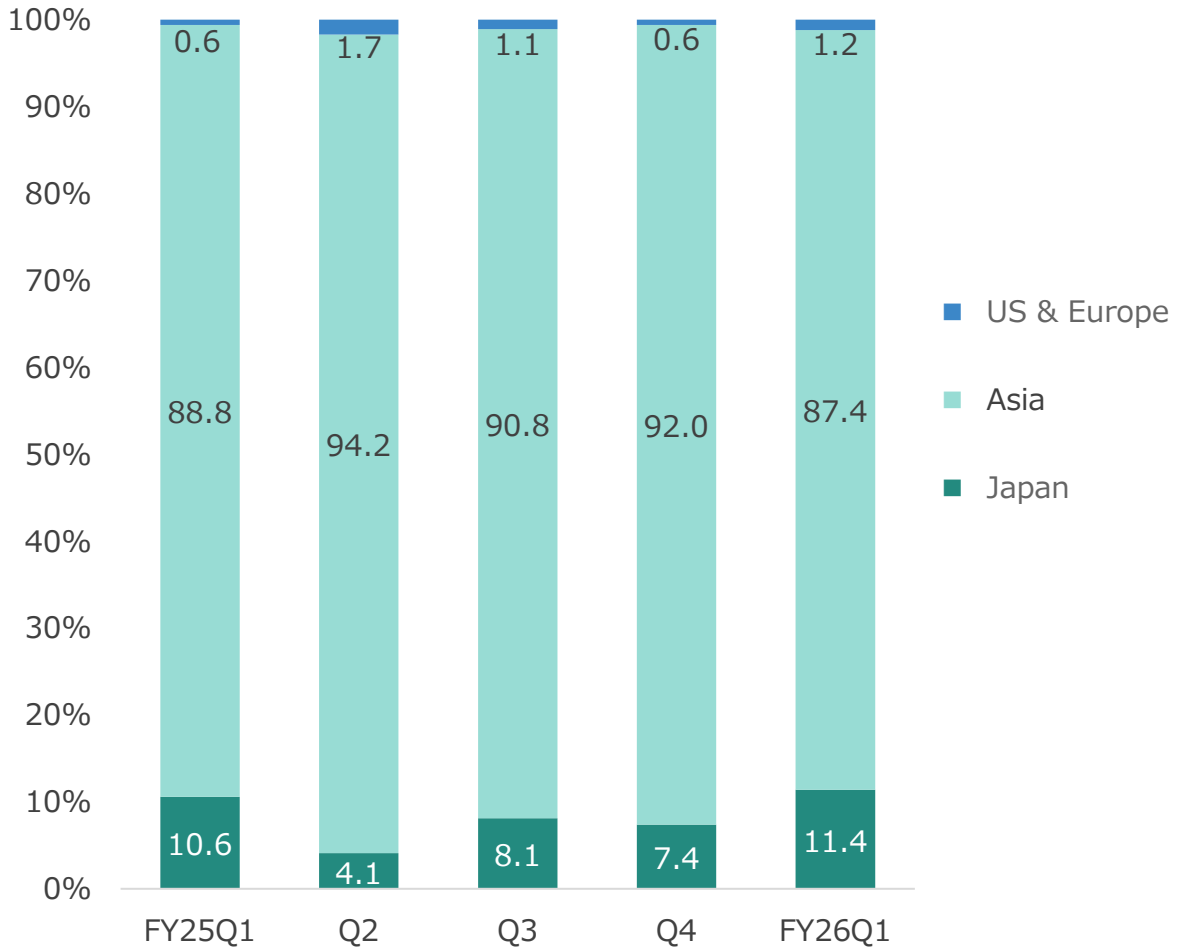
※1 Custom testers, Semiconductor probers, FPD test equipment, etc.
※2 Test sockets for semiconductors, Probe units for FPDs

# Quarterly Net Sales by Region

## Net Sales

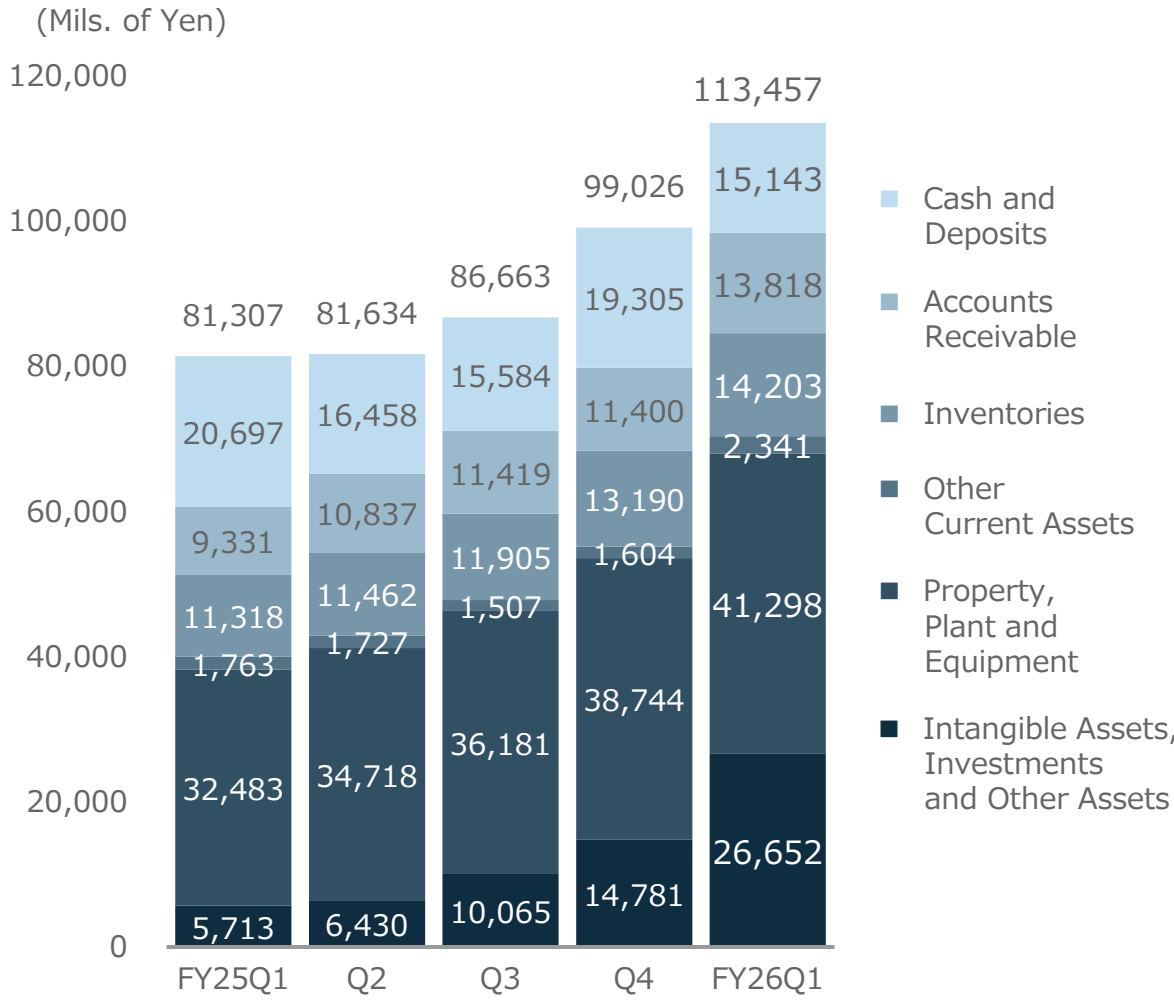



## Percentage of sales

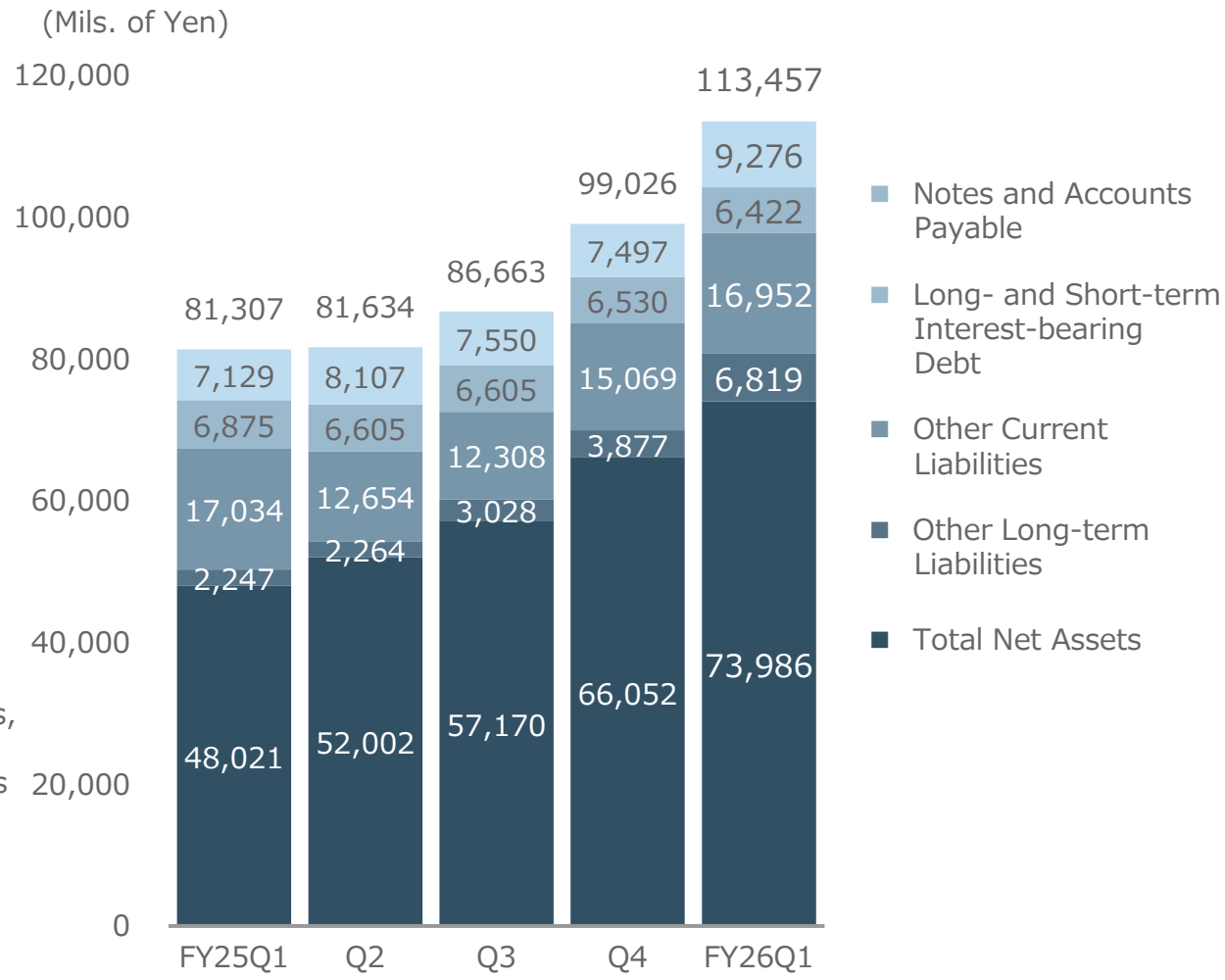


# Consolidated Balance Sheet

## Assets



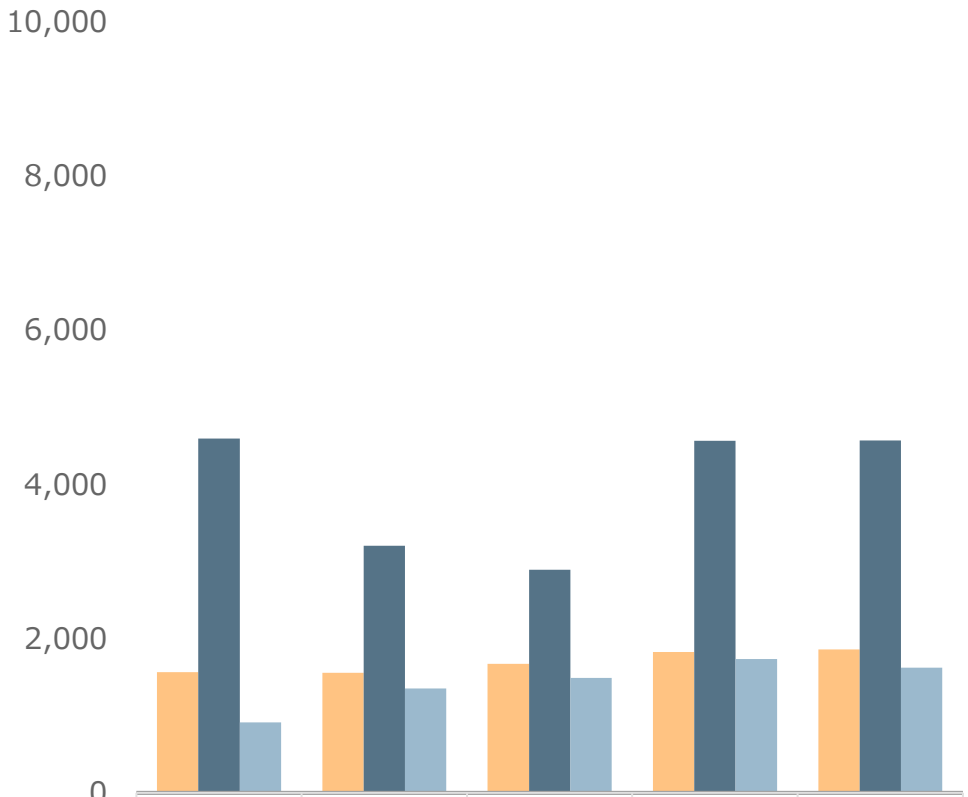

## Liabilities & Net Assets



# Investments/Cash Flows

## Investment,etc.

(Mils. of Yen)

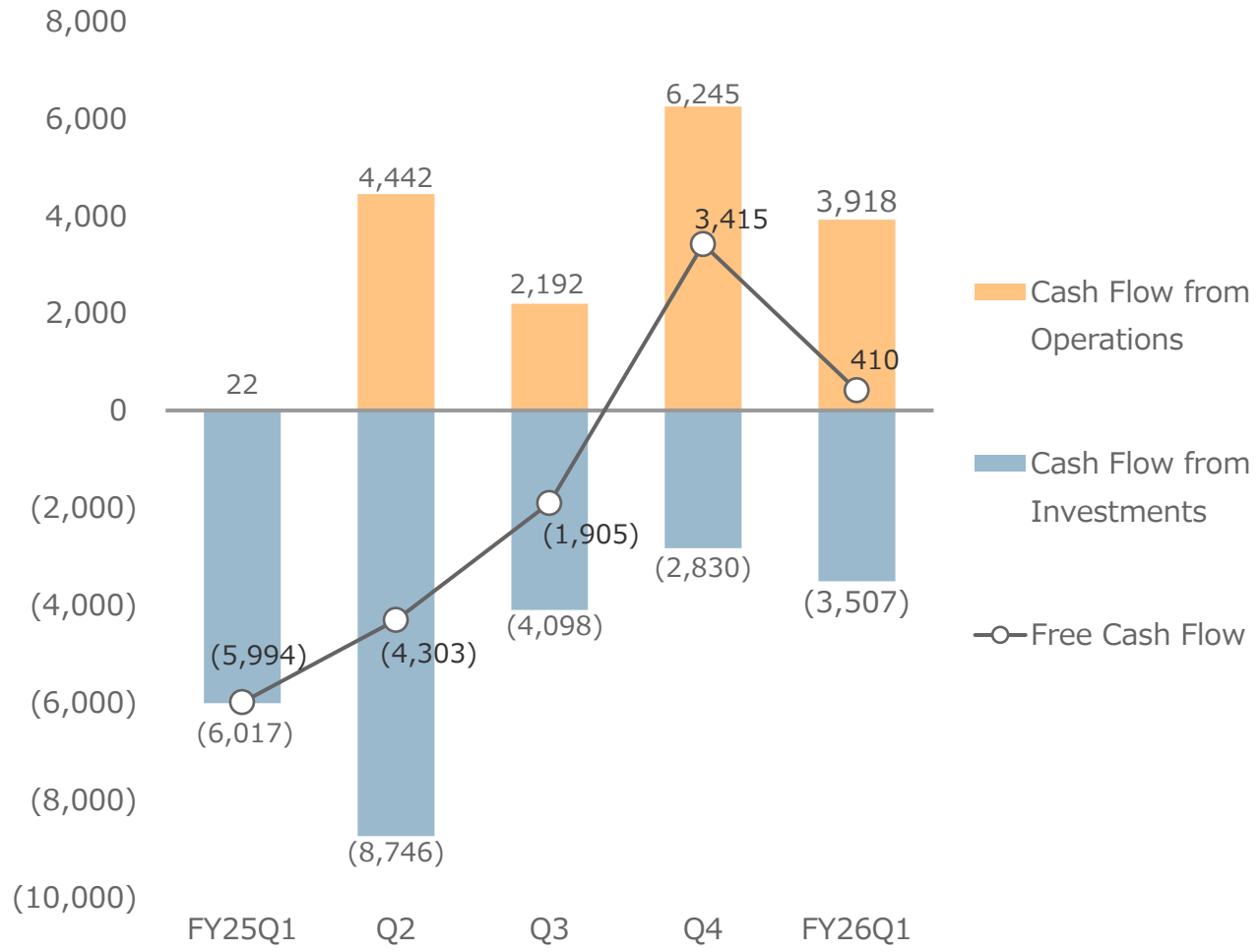



| | FY25Q1 | Q2 | Q3 | Q4 | FY26Q1 |
|---|---|---|---|---|---|
| R&D | 1,564 | 1,555 | 1,673 | 1,825 | 1,859 |
| CAPEX | 4,592 | 3,203 | 2,893 | 4,563 | 4,568 |
| Depreciation | 914 | 1,355 | 1,489 | 1,735 | 1,624 |

※ Including construction in progress

## Cash Flows

(Mils. of Yen)



# Forecasts

# Financial Forecast

(Mils. of Yen)

| | FY12/2025 | FY12/2026 | | | | | |
|---|---|---|---|---|---|---|---|
| | Jan.-Jun. ⓐ | As of Feb.13 (Jan.-Jun.) ⓑ | Jan.-Jun. (New) ⓒ | As of May.13 (△) ⓒ-ⓑ | As of May.13 (%) | YoY (△) ⓒ-ⓐ | YoY (%) |
| Net Sales | 33,120 | 43,900 | 45,700 | +1,800 | +4.1% | +12,579 | +38.0% |
| Probe Card | 32,199 | 43,200 | 45,000 | +1,800 | +4.2% | +12,800 | +39.8% |
| TE | 921 | 700 | 700 | +0 | +0.0% | (221) | (24.0%) |
| Operating profit | 7,569 | 12,300 | 12,900 | +600 | +4.9% | +5,330 | +70.4% |
| Ordinary profit | 7,394 | 11,800 | 12,700 | +900 | +7.6% | +5,305 | +71.7% |
| Net Income Attributable to Owner of Parent | 4,774 | 8,200 | 9,200 | +1,000 | +12.2% | +4,425 | +92.7% |

- FX rate assumption for FY12/2026: JPY 153.00 to USD, JPY 0.10 to KRW

# Financial Forecast

| (Mils. of Yen) | FY12/2025 | FY12/2026 | | |
|---|---|---|---|---|
| | Jan.-Sep. | Jan.-Sep. (New) | YoY | |
| | | | (△) | (%) |
| Net Sales | 50,412 | 71,600 | +21,187 | +42.0% |
| Probe Card | 49,117 | 70,400 | +21,282 | +43.3% |
| TE | 1,295 | 1,200 | (95) | (7.3%) |
| Operating profit | 11,300 | 21,900 | +10,599 | +93.8% |
| Ordinary profit | 11,273 | 21,400 | +10,126 | +89.8% |
| Net Income Attributable to Owner of Parent | 7,084 | 15,200 | +8,115 | +114.5% |

- FX rate assumption for FY12/2026: JPY 153.00 to USD, JPY 0.10 to KRW

# Regarding the Sales Outlook

## Revision of Revenue Outlook

- While the probe card market is expected to grow by 14% year-on-year in 2026 compared with 2025, the Group now expects its full-year revenue growth to significantly exceed the 26% growth rate previously assumed for the 2024–2025 period. This outlook revision reflects the smooth ramp-up of production capacity following the successful start-up of newly installed equipment.

※These forecasts are based on information available as of the date of announcement and are subject to change due to various factors. Actual results may differ materially from these forecasts.

# Glossary and Main Products

# Glossary

**Wafer:** Circular crystalline silicon (Si) or gallium arsenide (GaAs) sliced into a thin disk substrate used for semiconductor electrical circuits.

**Chip/Die:** Dies and chips are small semiconductor devices.
A semiconductor wafer is diced into many pieces, and each of these pieces is called a die or chip.

**IC:** Integrated circuit.

**Memory IC:** An integrated circuit made out of millions of capacitors and transistors that can store data such as DRAM, NAND Flash and etc.

**Logic IC**: An integrated circuit that performs logic functions.

**DRAM:** Dynamic random access memory.
A type of volatile memory with a wide range of uses including main storage for computers and general-purpose memory.

**NAND-Type Flash Memory:** A type of non-volatile memory that cannot be deleted even when the external power supply is interrupted. Used for USB memory, digital camera memory cards, mobile music players and mobile phone memory. Created by Toshiba in 1987.

**LSI:** Large-scale integrated circuit.
Called VLSI or ULSI when the transistor's degree of integration is increased.

**Micro Computer:** An IC that integrates memory and a microprocessor for arithmetic processing on one chip. Recently, the word "microcomputer" is often used to refer to those incorporated in home appliances or other products for electronic control.

**System on Chip (SoC) / System LSI:** Large-scale IC containing nearly an entire system on one chip. Combines multiple functions previously spread across multiple ICs onto one chip. Realizes small, high-performance machinery. Mainly used in processors and memory, input/output, interface and telecommunications circuitry.

**Flip Chip**: Flip chips have bump electrodes on the chip surface for the purpose of high-density surface mounting of IC chips on circuit boards. The bumps and wiring board terminals are connected with solder or conductive adhesive.

**Bump:** Bumps are solder bumps formed on IC pads. Bumps are normally formed with gold (Au) or solder and are used primarily in flip chips for connection to substrates.

**Bonding Pad:** Supply of power voltage to the chip and signal exchanges with exterior are normally conducted through the lead. The bonding pads are metal electrodes around the chip connecting this lead with each terminal on internal circuitry.

**IoT:** Internet of Things, allowing physical devices to be sensed or controlled remotely across existing internet infrastructure.

**FPD:** Flat panel display.

**LCD:** liquid crystal display.

# Glossary

**Wafer Test / Probe Test:** An electrical test conducted by placing a probe needle on a wafer chip bonding pad.

**Final Test / Package Test:** Electrical testing of assembled ICs.

**DUT:** Device under test.

**Area Array:** A state which has test pads in a grid array on the surface of a chip.

**Cantilever Probe Card**: Also called a cantilever needle. A probe card using a one-sided needle probe as a fulcrum. Shaped by hand.

**Advanced Probe Card:** Probe cards other than the cantilever type.

**Vertical Probe Cards**: A vertical probe card is a probe card in which probe needles are vertical to the substrate. Vertical probe cards are suitable for area array, small pad, low voltage, low needle pressure, and high frequency measurement.

**MEMS:** Micro-Electro-Mechanical Systems.

**MEMS Type Probe Card:** MEMS type probe cards are probe cards using MEMS technology. They have a structure that allows the mechanical movement of probe terminals.

**DFT:** Design for testability

**BIST:** Built In Self Test

**AI(Artificial Intelligence)**: The simulation of human intelligence processes by machines. It generally needs various type of semiconductors like image sensors.

**Generative AI**: automatically creates diverse content, including images, videos, and text. It learns from extensive pre-analyzed data, enabling the generation of new content. High-performance semiconductors like GPUs or HBMs are crucial for effective generative AI.

**GPU (Graphics Processing Unit ):**A semiconductor chip that handles complex data calculations, including 3D graphics processing. It excels in parallel computing. When combined with HBM, it enables even faster performance, especially for generative AI.

**HBM (High Bandwidth Memory) :** A type of DRAM known for its wide bandwidth and high-power efficiency. By stacking DRAM chips and connecting them to a processor using multiple buses, it achieves fast and large-capacity data transfer. It is primarily packaged with GPUs/CPU and used in HPCs and AI servers.

**HPC(High Performance Computing) :** A technology that performs complex computational processing on massive data at high speeds. It uses high-performance processors to handle big data efficiently.

**General-purpose server :** A computer or program that performs necessary processing through a network in response to requests from users.

**AI server:** A specialized server designed specifically for training and inference of generative AI. It is equipped with powerful CPUs, GPUs, HBM, and other devices, providing higher computational capabilities, large memory storage, high bandwidth, and low latency.

**Data center** :A facility designed to securely store servers and network equipment. When investments in data centers increase, there is often a higher demand for general-purpose servers, which in turn can lead to an increased need for DRAM chips.

# Our Products

## Probe Cards

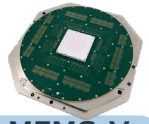
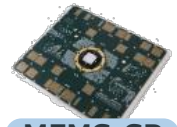
**U-Probe:** Our core product, realizing the world's first wafer-scale probing created with MJC's proprietary MEMS probe "micro-cantilever" and global top-level thin-film multilayer technology. With a bare minimum of contacting times via a crescent arrangement for DRAM, this product is currently the industry standard. Mainly used for memory testing on DRAM and flash memory.

**SP-Probe:** Vertical spring pin-type probe card suitable for 12-inch wafer batch measurements. Mainly used for testing NAND flash memory.

**MEMS-V / Vertical-Probe:** Vertical needle-type probe card used for testing highly integrated, high-speed multi-pin logic devices. Provides flexible support for a variety of pad and fine pitch arrangements and is suitable for multiple individual simultaneous measurements during testing of SoC and other advanced logic devices.

**MEMS-SP**: Probe card used for MEMS probe developed for testing SoC devices and other flip chip-type logic devices.

**Main Applications for MJC Probe Card Products**

| | Memory | | Logic | |
|---|---|---|---|---|
| | DRAM | Flash | SoC | |
| Vertical | |  SP-Probe |  Vertical-Probe |  SP−Probe |
| MEMS Type |  U-Probe |  |  MEMS-V |  MEMS-SP |

# Our Products

## Test Equipment

**Semiconductor Tester:** A system that gives electrical signals to a semiconductor device to compare output signals with expected values.

**Wafer Prober:** A system that handles the wafer to make contact in the designated position on the device.

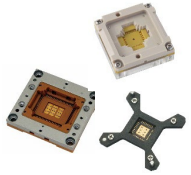
**Test Socket**: In the final inspection of semiconductor manufacturing, a fixture is used to electrically connect the packaged device and tester. There are two types: 'J-Contacts,' suitable for high-frequency and high-performance devices, and 'BeeContacts,' which have a unique spring probe structure with excellent contact stability.

**RF Probe:** RF Probe for High-frequency Measurement, Such as Radio Frequency and Microwave Signals.

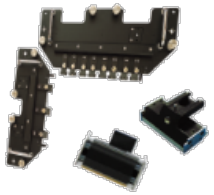
**Probe Unit:** Probe card with a built-in LCD prober. This blade-type unit developed by MJC is an industry standard.


Semiconductor Tester

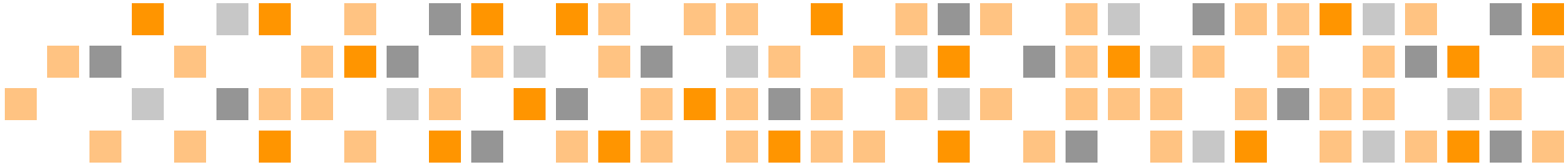

Wafer Prober


Test Socket


RF Probe


Probe Unit

MJC YOUR Best Partner, MJC Anytime Anywhere



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